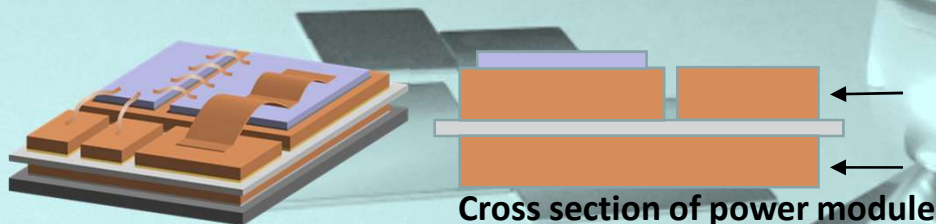


Active Brazing Filler Metal/Copper Composite Material

Applications

- ✓ Ceramics circuit board



Features

- ✓ Thick copper electrode



Thickness of 0.8 mm or more is possible

- ✓ Non etching process



0.3mm pitch is possible

- ✓ Environmentally friendly



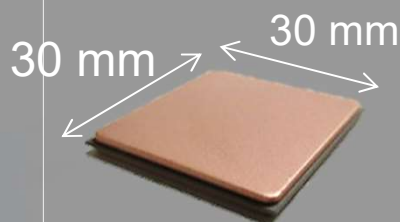
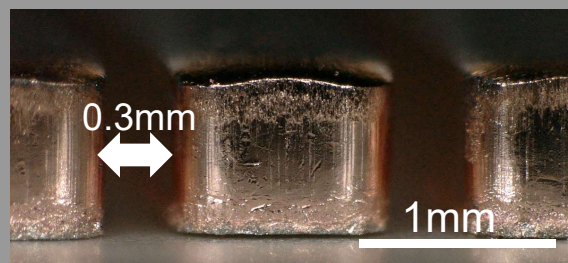
Organic free

- ✓ High thermal durability

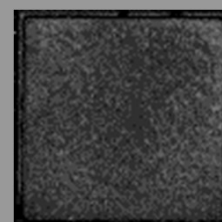
Thermal cycle test condition :
-50~175deg.C, Cycle time 30 min each

Sample size

Cu : 0.8 mm
Si₃N₄ : 0.32 mm
Cu : 0.8 mm



After
1,500 cyc.



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